

CDCLVP111-EP

SCAS933-DECEMBER 2012

LOW-VOLTAGE 1:10 LVPECL WITH SELECTABLE INPUT CLOCK DRIVER

Check for Samples: CDCLVP111-EP

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FEATURES

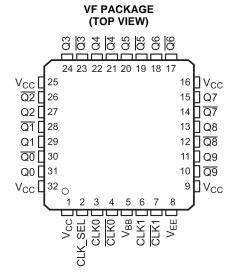
- Distributes One Differential Clock Input Pair LVPECL to 10 Differential LVPECL
- Fully Compatible With LVECL and LVPECL
- Supports a Wide Supply Voltage Range From 2.375 V to 3.8 V
- Selectable Clock Input Through CLK_SEL
- Low-Output Skew (Typ 15 ps) for Clock-Distribution Applications
 - Additive Jitter Less Than 1 ps
 - Propagation Delay Less Than 355 ps
 - Open Input Default State
 - LVDS, CML, SSTL input compatible
- V_{BB} Reference Voltage Output for Single-Ended Clocking
- Available in a 32-Pin LQFP Package
- Frequency Range From DC to 3.5 GHz
- Pin-to-Pin Compatible With MC100 Series EP111, ES6111, LVEP111, PTN1111

APPLICATIONS

- Designed for Driving 50 Ω Transmission Lines
- High Performance Clock Distribution

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
 - One Assembly and Test Site
- One Fabrication Site
- Available in Military (–55°C to 125°C) Temperature Range ⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability



(1) Custom temperature ranges available

DESCRIPTION

The CDCLVP111 clock driver distributes one differential clock pair of LVPECL input, (CLK0, CLK1) to ten pairs of differential LVPECL clock (Q0, Q9) outputs with minimum skew for clock distribution. The CDCLVP111 can accept two clock sources into an input multiplexer. The CDCLVP111 is specifically designed for driving $50-\Omega$ transmission lines. When an output pin is not used, leaving it open is recommended to reduce power consumption. If only one of the output pins from a differential pair is used, the other output pin must be identically terminated to 50Ω .

The V_{BB} reference voltage output is used if single-ended input operation is required. In this case, the V_{BB} pin should be connected to CLK0 and bypassed to GND via a 10-nF capacitor.

However, for high-speed performance up to 3.5 GHz, the differential mode is strongly recommended.

The CDCLVP111 is characterized for operation from -55°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Table 1. FUNCTION TABLE

CLK_SEL	ACTIVE CLOCK INPUT
0	CLK0, CLK0
1	CLK1, CLK1

Table 2. ORDERING INFORMATION⁽¹⁾

TJ	PACKAGE	ORDERABLE PART NUMBER	TOP-SIDE MARKING	VID NUMBER
-55°C to 125°C	LQFP - VF	CDCLVP111MVFREP	LVP111MEP	V62/12624-01XE

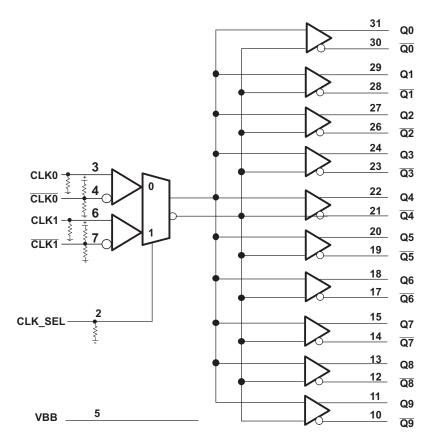
(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DEVICE INFORMATION



PIN FUNCTIONS⁽¹⁾

	PIN	DESCRIPTION				
NAME	NO.	DESCRIPTION				
CLK_SEL	2	Clock select. Used to select between CLK0 and CLK1 input pairs. LVTTL/LVCMOS functionality compatible.				
CLK0, CLK0	3, 4					
CLK1, CLK1	6, 7	Differential LVECL/LVPECL input pair				
Q [9:0]	11, 13, 15, 18, 20, 22, 24, 27, 29, 31	LVECL/LVPECL clock outputs, these outputs provide low-skew copies of CLKn.				
Q[9:0]	10, 12, 14, 17, 19, 21,23, 26, 28, 30	LVECL/LVPECL complementary clock outputs, these outputs provide copies of CLKn.				
V _{BB}	5	Reference voltage output for single-ended input operation				
V _{CC}	1, 9, 16, 25, 32	Supply voltage				
V _{EE}	8	Device ground or negative supply voltage in ECL mode				

(1) CLKn, CLK_SEL pull down resistor = 75 k Ω ; \overline{CLKn} pull up resistor = 37.5 k Ω ; \overline{CLKn} pull down resistor = 50 k Ω .

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

		VALUE	UNIT
V_{CC}	Supply voltage (Relative to V _{EE})	-0.3 to 4.6	V
VI	Input voltage	–0.3 to V _{CC} + 0.5	V
Vo	Output voltage	–0.3 to V _{CC} + 0.5	V
I _{IN}	Input current	±20	mA
V_{EE}	Negative supply voltage (Relative to V _{CC})	-4.6 to 0.3	V
I_{BB}	Sink/source current	-1 to 1	mA
I _O	DC output current	-50	mA
T _{stg}	Storage temperature range	-65 to 150	°C
TJ	Maximum operating junction temperature	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

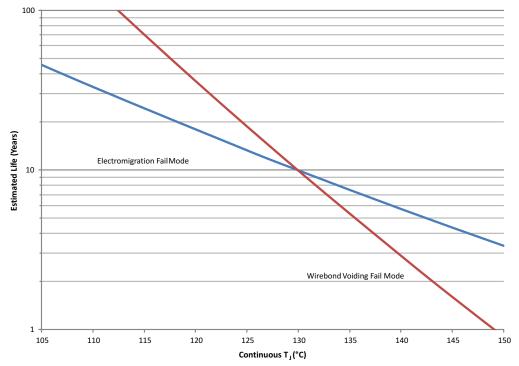
		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage (relative to V_{EE})	2.375	2.5/3.3	3.8	V
TJ	Operating junction temperature	-55		125	°C

PACKAGE THERMAL IMPEDANCE, VF (LQFP)

		TEST CONDITION	VALUE	UNIT
		0 LFM	74	°C/W
0	Thermal register as junction to embient ⁽¹⁾	150 LFM	66	°C/W
θ_{JA}	Thermal resistance junction to ambient ⁽¹⁾	250 LFM	64	°C/W
		500 LFM	61	°C/W
θ _{JC}	Thermal resistance junction to case		39	°C/W

(1) According to JESD 51-7 standard.





- (1) See data sheet for absolute maximum and minimum recommended operating conditions.
- (2) Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).

Figure 1. CDCLVP111 in 32/VF Package Operating Life Derating Chart

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STRUMENTS

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LVECL DC ELECTRICAL CHARACTERISTICS

	PARAMETER	TEST CONDITION	6	MIN	TYP	MAX	UNIT
I _{EE}	Supply internal current	Absolute value of current	–55°C, 25°C, 125°C	35		85	mA
	Output and internal	All outputs termineted EQ Q to V 2 V	–55°C, 25°C			385	mA
I _{CC}	supply current	All outputs terminated 50 Ω to V_{CC} – 2 V	125°C			405	mA
I _{IN}	Input current	Includes pullup/pulldown resistors, $V_{IH} = V_{CC}$, $V_{IL} = V_{CC}$ - 2 V	–55°C, 25°C, 125°C	-150		150	μA
v	Internally generated	For $V_{EE} = -3$ to -3.8 V, I _{BB} = -0.2 mA	–55°C, 25°C, 125°C	-1.45	-1.3	-1.125	V
V _{BB}	bias voltage	$V_{EE} = -2.375 \text{ to } -2.75 \text{ V},$ $I_{BB} = -0.2 \text{ mA}$	–55°C, 25°C, 125°C	-1.4	-1.25	-1.1	v
VIH	High-level input voltage (CLK_SEL)		–55°C, 25°C, 125°C	-1.165		-0.88	V
V _{IL}	Low-level input voltage (CLK_SEL)		–55°C, 25°C, 125°C	-1.81		-1.475	V
V _{ID}	Input amplitude (CLKn, CLKn)	Difference of input, See $^{(1)}\left V_{IH}-V_{IL}\right $	–55°C, 25°C, 125°C	0.5		1.3	V
V _{CM}	Common-mode voltage (CLKn, CLKn)	DC offset relative to V_{EE}	–55°C, 25°C, 125°C	V _{EE} + 1		-0.3	V
			–55°C	-1.26		-0.85	
V _{он}	High-level output voltage	I _{OH} = -21 mA	25°C	-1.2		-0.85	V
			125°C	-1.15		-0.8	
	Low-level output	L _ 5 mA	25°C	-1.85		-1.425	V
V _{OL}	voltage	$I_{OL} = -5 \text{ mA}$	–55°C, 125°C	-1.85		-1.25	v
V _{OD}	Differential output voltage swing	Terminated with 50 Ω to V _{CC} –2 V, See Figure 4	–55°C, 25°C, 125°C	400			mV

(1) V_{ID} minimum and maximum is required to maintain ac specifications, actual device function tolerates a minimum V_{ID} of 100 mV.



LVPECL DC ELECTRICAL CHARACTERISTICS

Vsupply: $V_{CC} = 2.375$ V to 3.8 V, $V_{EE} = 0$ V over operating temperature range $T_J = -55^{\circ}C$ to 125°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
I _{EE}	Supply internal current	Absolute value of current	–55°C, 25°C, 125°C	35		85	mA
	Output and internal	All outputs terminated E0.0 to V 2.2V	-55°C, 25°C			385	mA
I _{CC}	supply current	All outputs terminated 50 Ω to V_{CC} – 2 V	125°C 405		ma		
I _{IN}	Input current	Includes pullup/pulldown resistors $V_{IH} = V_{CC}, V_{IL} = V_{CC}-2V$	–55°C, 25°C, 125°C	-150		150	μA
	Internally generated	V_{CC} = 3 to 3.8 V, $I_{BB}\text{=}$ –0.2 mA	–55°C, 25°C, 125°C	V _{CC} – 1.45	V _{CC} – 1.3	V _{CC} – 1.125	
V _{BB}	bias voltage	V_{CC} = 2.375 to 2.75 V, I_{BB} = $-0.2\mbox{ mA}$	–55°C, 25°C, 125°C	V _{CC} – 1.4	V _{CC} – 1.25	V _{CC} – 1.1	V
V _{IH}	High-level input voltage (CLK_SEL)		–55°C, 25°C, 125°C	V _{CC} – 1.165		V _{CC} – 0.88	V
VIL	Low-level input voltage (CLK_SEL)		–55°C, 25°C, 125°C	V _{CC} – 1.81		V _{CC} – 1.475	V
V_{ID}	Input amplitude (CLKn, CLKn)	Difference of inpu, see $^{(1)},\left V_{IH}-V_{IL}\right $	–55°C, 25°C, 125°C	0.5		1.3	V
V _{CM}	Common-mode voltage (CLKn, CLKn)	DC offset relative to V_{EE}	–55°C, 25°C, 125°C	1		$V_{CC} - 0.3$	V
			–55°C	V _{CC} – 1.26		V _{CC} – 0.85	
V _{OH}	High-level output voltage	I _{OH} = -21 mA	25°C	V _{CC} – 1.2		V _{CC} – 0.85	V
			125°C	V _{CC} – 1.15		$V_{CC} - 0.8$	
V _{OL}	Low-level output	I _{OL} = -5 mA	25°C	V _{CC} – 1.85		V _{CC} – 1.425	V
V OL	voltage		–55°C, 125°C	V _{CC} – 1.85		V _{CC} – 1.25	v
V _{OD}	Differential output voltage swing	Terminated with 50 Ω to V _{CC} - 2 V, See Figure 4	–55°C, 25°C, 125°C	400			mV

(1) V_{ID} minimum and maximum is required to maintain ac specifications, actual device function tolerates a minimum V_{ID} of 100 mV.

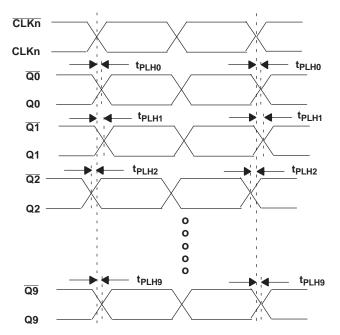
AC ELECTRICAL CHARACTERISTICS

Vsupply: $V_{CC} = 2.375$ V to 3.8 V, $V_{EE} = 0$ V or LVECL/LVPECL input $V_{CC} = 0$ V, $V_{EE} = -2.375$ V to -3.8 V over operating temperature range $T_J = -55^{\circ}$ C to 125°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{pd}	Differential propagation delay CLKn, CLKn to all Q0, Q0 Q9, Q9	See Note D in Figure 2	200		355	ps
t _{sk(o)}	Output-to-output skew	See Notes A and D in Figure 2		15	50	ps
t _{sk(pp)}	Part-to-part skew	See Notes B and D in Figure 2		70		ps
t _{aj}	Additive phase jitter ⁽¹⁾	Integration bandwidth of 20 kHz to 20 MHz, fout = 200 MHz at 25°C		0.125	0.8	ps
f _(max)	Maximum frequency ⁽¹⁾	Functional up to 3.5 GHz, see Figure 4			3500	MHz
t _r /t _f	Output rise and fall time (20%, 80%)	See Note D in Figure 2			240	ps

(1) Specification is guaranteed by bench characterization and is not tested in production.





- A. Output skew is calculated as the greater of: The difference between the fastest and the slowest t_{PLHn} (n = 0, 1,...9) or the difference between the fastest and the slowest t_{PHLn} (n = 0, 1,...9).
- B. Part-to-part skew, is calculated as the greater of: The difference between the fastest and the slowest t_{PLHn} (n = 0, 1,...9) across multiple devices or the difference between the fastest and the slowest t_{PHLn} (n = 0, 1,...9) across multiple devices.
- C. Typical value measured at ambient when clock input is 155.52 MHz for an integration bandwidth of 20 kHz to 5 MHz.
- D. Input conditions: V_{CM} = 1 V, V_{ID} = 0.5 V and F_{IN} = 1 GHz.



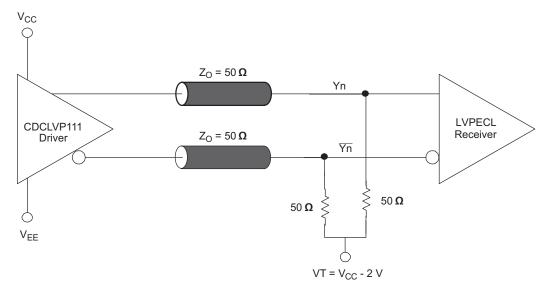


Figure 3. Typical Termination for Output Driver (See the Interfacing Between LVPECL, LVDS, and CML Application Note, Literature Number SCAA056)



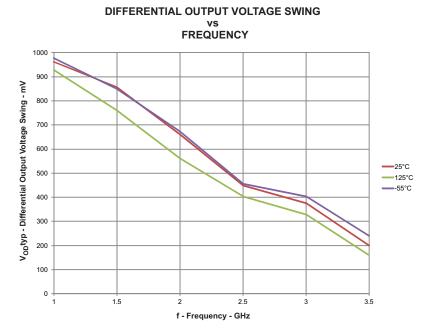


Figure 4. LVPECL Input Using CLK0 Pair, V_{CC} = 2.375 V, V_{CM} = 1 V, V_{ID} = 0.5 V



6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
CDCLVP111MVFREP	ACTIVE	LQFP	VF	32	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-3-260C-168 HR	-55 to 125	LVP111MEP	Samples
V62/12624-01XE	ACTIVE	LQFP	VF	32	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-3-260C-168 HR	-55 to 125	LVP111MEP	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

6-Feb-2020

OTHER QUALIFIED VERSIONS OF CDCLVP111-EP :

• Catalog: CDCLVP111

• Space: CDCLVP111-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCLVP111MVFREP	LQFP	VF	32	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

19-Dec-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCLVP111MVFREP	LQFP	VF	32	1000	367.0	367.0	38.0

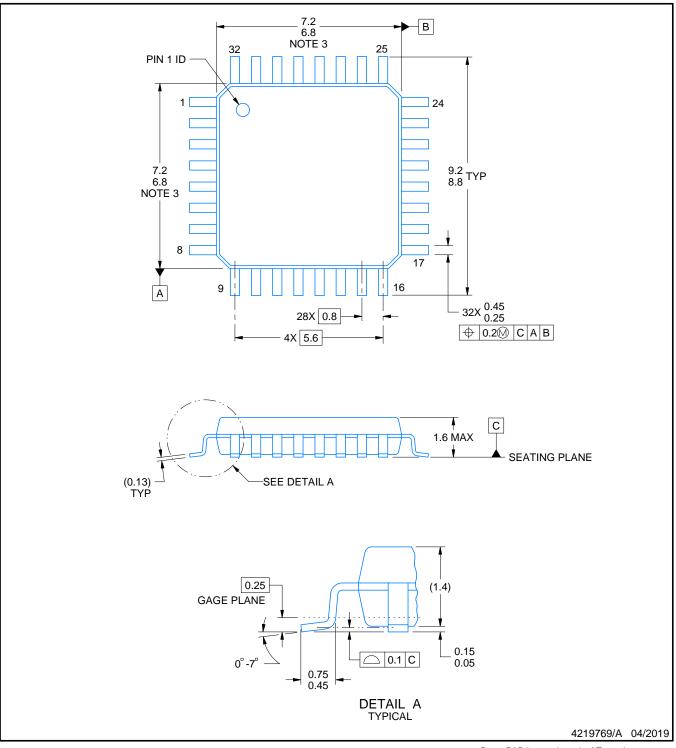
VF0032A



PACKAGE OUTLINE

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



NOTES:

PowerPAD is a trademark of Texas Instruments.

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.2. This drawing is subject to change without notice.3. This dimension does not include mold flash, protrusions, or gate burrs.

- 4. Reference JEDEC registration MS-026.

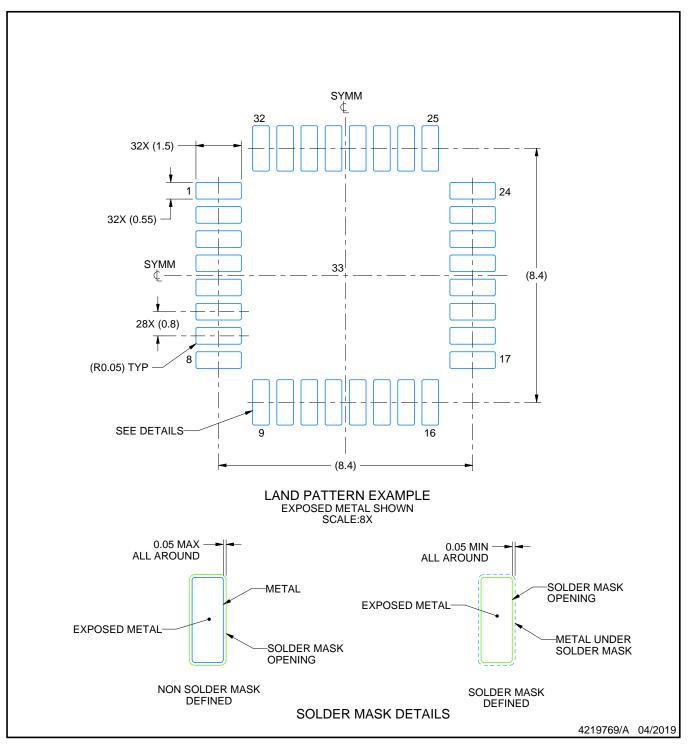


VF0032A

EXAMPLE BOARD LAYOUT

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

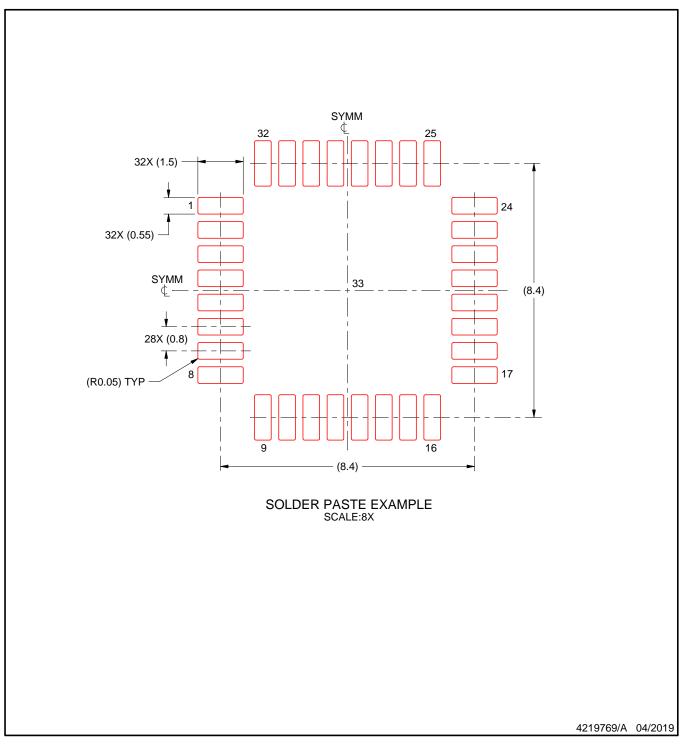


VF0032A

EXAMPLE STENCIL DESIGN

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



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